



SKJERVEN
MORRILL
MACPHERSON LLP



Docket No.: NS-3877-2D US

March 8, 2001

Commissioner For Patents
Washington, D.C. 20231

Re: Applicants: Mostafazadeh, Shahram; Smith, Joseph O.
Assignee: National Semiconductor Corporation
Title: Lead Frame Chip Scale Package
Serial No.: 09/625,071
Examiner: S. Clark
Docket No.: NS-3877-2D US

Filed: July 25, 2000
Group Art Unit: 2815

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Dear Sir:

Transmitted herewith are the following documents in the above-identified application:

- (1) Return Receipt Postcard;
- (2) This Transmittal Letter (in duplicate);
- (3) Response to Office Action of November 27, 2000 (4 pages);
- (4) Appendix A (Amended Claim 11) (1 page); and
- (5) Petition for (1) Month Extension Of Time.

- ☐ No additional fee is required.
☒ The fee has been calculated as shown below:

CLAIMS AS AMENDED

	Claims Remaining <u>After Amendment</u>		Highest No. Previously Paid For		Present Extra	Rate	Additional Fee
Total Claims	7	Minus	20	=	0	x \$18	\$ 0.00
Independent Claims	1	Minus	3	=	0	x \$80	\$ 0.00
<input type="checkbox"/>	Fee of _____ for the first filing of one or more multiple dependent claims per application						\$
<input checked="" type="checkbox"/>	Fee for Request for Extension of Time (one month)						\$ 110.00
<u>Total additional fee for this Amendment:</u>							\$ 110.00
<input checked="" type="checkbox"/>	Conditional Petition for Extension of Time: If an extension of time is required for timely filing of the enclosed document(s) after all papers filed with this transmittal have been considered, an extension of time is hereby requested.						
<input checked="" type="checkbox"/>	Please charge our Deposit Account No. 19-2386 in the amount of						\$ 110.00
<input checked="" type="checkbox"/>	Also, charge any additional fees required and credit any overpayment to our Deposit Account No. 19-2386.						
Total:							\$ 110.00

I hereby certify that this correspondence is being deposited with
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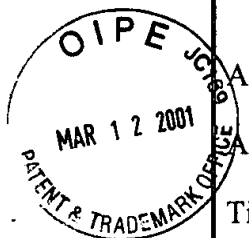
Attorney for Applicants

Date of Signature

Respectfully submitted,

Edward C. Kwok
Attorney for Applicants
Reg. No. 33,938

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



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#5B
Amend

San Jose, California
March 8, 2001

COMMISSIONER FOR PATENTS
Washington, D. C. 20231

J. McInnes
3/19/01

AMENDMENT

Dear Sir:

This submission responds to the Office Action of November 27, 2000. Please amend the above-referenced patent application as follows:

IN THE CLAIMS

Please amend Claim 11 as follows:

11. (Amended) An integrated circuit package for accommodating a semiconductor die, comprising:

a planar lead frame comprising (a) a die attach pad supporting said semiconductor die on an upper surface of said die attach pad, and (b) substantially planar conductive leads positioned around an outer periphery of said die attach pad, wherein each of said conductive leads having a lower surface that is substantially

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